# **Simple, high-performance, isolated power supply design with PSR (no-opto) flyback**

**Marshall Beck July 2021**



1

# **Agenda**

- Isolation in industrial applications
- PSR flyback:
	- PSR vs conventional flyback, control/operation, and TI offerings
- PSR flyback simple design flow
- TI supporting content on PSR flyback design







# **Where to use isolation? In the US** Isolation

- **Safety** 
	- Mandatory by safety standards to isolate the user from the hazardous voltage of a power supply. Protect user from ESD and surge events.
	- Typical applications: IP camera, solar inverter, factory automation field site
- **Break ground loop, mitigate noise**
	- Installed to break the ground loop interference for noise-sensitive applications
	- Typical applications : PLCs, solar inverters, building automation (ie. RS232/485, etc.)
- **Inversion, level shifting & multiple rails**
	- Isolated output voltage can be conveniently configured as multiple isolated outputs, as a negative voltage rail or as a level-shifted voltage rail.
	- Typical applications : test and measurement, medical, e-bike, HVAC, motor drives





# **Isolated power – Simplify signal integrity!**

- Typical communication protocols: **RS422/485, RS232, RS285, LVDS, Ethernet B5. LVDS. Ethernet**
- Long cabling causes transient voltage differences and **possible errors!** e errors
- **Solution: Isolate the TX and RX power!**



# **Isolated power – Simplify your power tree!**

- Isolated output voltages can be conveniently configured as **multiple isolated outputs**, as a **negative voltage rail** or as a **level-shifted voltage rail**.
- **Example use cases**: Positive/negative rails for differential digital communications, op-amp, isolated bias supply for gate driver





## **Conventional PSR flyback vs. Aux-less PSR flyback**



### **Conventional PSR flyback advantages:**

- Increased design flexibility with external compensation and tertiary winding or optocoupler feedback
- Operates in CCM (fixed frequency) or DCM mode



### **Aux-less PSR flyback advantages:**

- Eliminates opto-coupler or tertiary winding with only one component crossing isolation barrier
- Extremely tight load regulation (±1%)
- Operates in DCM or Boundary Mode
- 7 • DCM and zero current switching enables high efficiency



# **PSR flyback converter – no opto, no aux winding**



# **PSR flyback DC/DC family overview**





### **LM25183-Q1/LM25184-Q1**

### **Highest power density 42V, 2.5A/4A primary side regulated (PSR) flyback converter with 65V integrated power MOSFET**

### *Features Benefits*

- Highest Power Density 42V PSR with tightest Output Regulation in its class
- **65V, 2.5A/4A internal power MOSFET**
- $\cdot$  4.5V–42V wide V<sub>IN</sub> range (abs max 45V)
	- $\circ$  3.5V minimum V<sub>IN</sub> after start-up
- **VOUT accuracy ±1% achievable**
	- $V_{\text{IN}} = 6V 42V$ ,  $V_{\text{OUT}} = 5V$ , 2% load to full load  $\circ$  T<sub>A</sub> = –40°C to 125°C
- **Boundary mode**, quasi-resonant operation
- Internal loop compensation, adjustable input UVLO
- External  $V_{CC}$  bias option for improved efficiency
- Adjustable or fixed internal 6ms soft-start
- Optional  $V_{\text{OUT}}$  temperature compensation
- **4 mm 4 mm WSON-8** WF package, 0.8mm pitch
- **AEC-Q100 grade 1**  $\Rightarrow$  125°C operating ambient range

### *Applications*

- **Factory automation, PLC**
- 

- ➢ No opto-coupler or transformer auxiliary winding needed
- $\triangleright$  Accurate V<sub>OUT</sub> regulation performance with sensing at zero current
- $\triangleright$  Low I<sub>0</sub> operation and external BIAS rail option enable high efficiency at light loads





**AEC-Q100 Grade 1**

# **LM25184 performance curves**

### Low-heat generation



Modest  $F_{SW}$  enables good transient performance and small magnetics



Figure 2. LM25184 EVM (Top Side), 56 mm × 36 mm



Typical Efficiency,  $V_{OUT}$  = 12 V



<1.7% variance from -40degC to 125degC

Figure 8-25. Positive Output Load Transient, 0.25 A to 0.5 A



Figure 8-14. CISPR 25 Class 5 Conducted EMI Plot | Figure 8-15. CISPR 25 Class 5 Conducted EMI Plot

Passes stringent EMC standards with only differential filtering



# **TI's simple design flow**





# **Design calculator tool**

### **Input power conditions Linput xfm spec and SCH and BOM**







### **Evaluate performance**







**Total Solution Size (buffered by 25%)**  $220.4<sub>m</sub>$ 



### **Released reference designs**

#### **TIDA-010006**

#### Isolated IGBT gate driver power supply using integrated switch PSR flyback controller



### **TIDA-020014**

HEV/EV traction inverter power stage reference design with 3 types of IGBT/SiC bias supply solutions

#### **Design Features**

- + 4.5V to 45V input, +15V and -9V outputs, configurable into +20V, -4V outputs
- Directly driven by 12V car battery with increased safety level • Wide-Vin during very low dips in input voltage of 4.5V and up to 45V DC
- No Opto coupler
- Low IQ operation at no-load current
- High efficiency at light loads

#### **Tools & Resources**

- Expected complexity of the TI Design
	- + # of IC's: 5 (LM5180-Q1, TPS40210-Q1, LM76003-Q1\*2, SN6501-Q1/SN6505-Q1, LM74700-Q1\*3)
	- $\cdot$  # of passives:  $\sim$ 140 into 3 boards
	- · PCB dimensions: ~40mm\*40mm each board
	- # of PCB layers: 2
	- Firmware needs: N/A

TI Information - Selective Disclosure

#### **Design Benefits**

- . A comprehensive design with multiple bias supply solutions for IGBT/SiC isolated gate drivers in HEV/EV
- Multiple solutions including PSR Flyback Converter, Flyback Controller, Buck + Push-pull
- Small size, compact, cost effective
- Plug in connection to IGBT driver board for easy HV evaluation
- Compatible Isolated Gate Driver board included for customer evaluation



### **TIDA-020015**

4.5V to 70V input bias supply with power stage reference design for Automotive **IGBT/SiC** gate drivers

#### **Design Features**

- Directly driven by 12V car battery which eliminates risk from intermediate power rail failure
- VOUT accuracy ±1% achievable
- VIN = 4.5V-70V, VOUT = +15V & -9V, ~180mA, 5% regulation to full load
- TA =  $-40^{\circ}$ C to 125 $^{\circ}$ C
- Boundary mode, quasi-resonant operation
- · Internal loop compensation
- no need to extra clamping circuit, fits both 12V battery & 48V battery inputs
- Tested for ISO 7637-2:2004 conducted transient immunity compliance, including Load Dump

#### **Tools & Resources**

• Expected complexity of the TI Design

- + # of IC's: 2 (LM5180-Q1+LM74700-Q1)
- $\cdot$  # of passives: ~35
- PCB dimensions: ~40mm\*40mm
- # of PCB layers: 2
- · Firmware needs: N/A

### TIDACBL-0039 Intrinsic Safe Analog Input Module

#### **Features**

- . 1 to 4 channel-channel isolated Intrinsic Safe AI
- Supply for the Field Transmitters with output power
- limitation (short limited to 35mA ().
- Input protected against miswiring (wiring to 24V)
- Transmitter supply: 26 +/-1V, lout <35mA peak
- Input: short to L+ and GND protected, 24b accuracy

#### **Applications**

- Robotics Analog Input Module for IS application
- PLC Analog Input Module

#### **Additional details**



#### **Design Benefits**

- Easy-to-use, highly integrated, PSR flyback solution as Bias Power
- No opto-coupler or transformer auxiliary winding needed
- Low IQ operation at no-load current
- High efficiency at light loads
- Accurate V<sub>OUT</sub> regulation performance with sensing at zero current
- Low I<sub>o</sub> operation and external BIAS rail option enable high efficiency at light loads





**Benefits** 

- . Mis-wiring protections on the Analog Input
- High-accuracy LM5180 allows to minimise heat dissipation from LDO (which can be low drop LDO)





# **PSR flyback references**

[LM25184 Single-Output EVM User's Guide](http://www.ti.com/lit/pdf/SNVU680) 

[LM5180 Single-Output EVM User's Guide](http://www.ti.com/lit/pdf/SNVU592) 

[LM5180 Dual-Output EVM User's Guide](http://www.ti.com/lit/pdf/SNVU609) 

[How an Auxless PSR Flyback Converter can Increase PLC Reliability and Density](http://www.ti.com/lit/pdf/SLYT779) 

[Why Use PSR-Flyback Isolated Converters in Dual-Battery mHEV Systems](http://www.ti.com/lit/pdf/SLYT791) 

[PSR Flyback DC/DC Converter Transformer Design for mHEV Applications](http://www.ti.com/lit/pdf/SNVA805)

[Flyback Transformer Design Considerations for Efficiency and EMI](http://www.ti.com/lit/pdf/SLUP338) 

[Under the Hood of Flyback SMPS Designs](http://www.ti.com/lit/pdf/SLUP261) 



# **Conclusion**

- **Isolated power sockets exist everywhere!**
	- **Medical and test & measurement, sensors in factory and building automation**: split rails for signal conditioning circuit (ie. op-amp, DAC/ADC)
	- **Factory automation, building automation, communications, and solar**: isolated power needed to ensure high signal integrity, with more and more sensors & faster speeds, signal integrity concerns only increase!
	- **Inverters in HVAC Systems, E-bike, Motor Drives**: Isolated gate driver requires isolated gate bias. SiC requires tighter regulation which is a great fit for No-opto PSR flyback.





# **Thank you!**

# **PSR flyback converter – magnetic design considerations**



# **Engaging with the magnetic component vendor**



### **Flyback transformer losses**

### • **Copper** loss

- $\circ$  DC resistance depends on the wire cross-section and length (N, MLT)
- $\circ$  AC resistance depends on choice of wire diameter vs.  $F_{SW}$  and construction (layer stackup, proximity effects, gap effect) ss-section and le<br>re diameter vs. F<br> $B_{\text{DC}}$ , B<sub>AC</sub>, F<sub>SW</sub><br> $\frac{2}{2}$ ted in external cl vire cross-section and length (N,<br>
e of wire diameter vs.  $F_{SW}$  and  $C$ <br>
ect)<br>
istics,  $B_{DC}$ ,  $B_{AC}$ ,  $F_{SW}$ <br>  $E_{LEAK} = \frac{L_{LEAK} \cdot I_{SW-PK}^2}{2} \cdot F_{SW}$ <br>
dissipated in external clamp circ<br>
ated – depends on clamp level at **SeS**<br>wire cross-section and length<br>ce of wire diameter vs.  $F_{\text{SW}}$  and<br>fect)<br>rristics,  $B_{\text{DC}}$ ,  $B_{\text{AC}}$ ,  $F_{\text{SW}}$ <br> $P_{\text{LEAK}} = \frac{L_{\text{LEAK}} \cdot I_{\text{SW-PK}}^2}{2} \cdot F_{\text{SW}}$ <br>r dissipated in external clamp<br>vated – depends on c Fross-section and length (N, MLT)<br>wire diameter vs.  $F_{SW}$  and construction (layer<br>s,  $B_{DC}$ ,  $B_{AC}$ ,  $F_{SW}$ <br>=  $\frac{L_{LEAK} \cdot I_{SW-PK}^2}{2} \cdot F_{SW}$ <br>ipated in external clamp circuit or RC snubber<br>- depends on clamp level and leak

### • **Core** loss

 $\circ$  Related to core material characteristics, B<sub>DC</sub>, B<sub>AC</sub>, F<sub>SW</sub>

### • **External** loss

$$
\circ \text{ Leakage inductance energy} \qquad P_{LEAK} = \frac{L_{LEAK} \cdot I_{SW-PK}^2}{2} \cdot F_{SW}
$$

- Large percentage of this power dissipated in external clamp circuit or RC snubber
- **Magnetizing energy also dissipated depends on clamp level and leakage inductance**  $\sim$  -  $\mathsf{F}_{\mathsf{SW}}$ <br>ernal clamp circuit or RC snubber<br>n clamp level and leakage inductance



# **Flyback transformer – impact of leakage inductance**



### **Leakage inductance affects:**

- Conversion efficiency
- Voltage spikes during commutation
	- clamp circuits and snubbers
- Current slew rate & loss of volt-seconds
- H-field radiated EMI
- Cross regulation in multi-output designs





# **Flyback transformer design – impact on efficiency / x-reg**

### 1. Guidelines to **optimize efficiency**

- Choose the transformer **turns ratio** for best efficiency and duty cycle range
- Minimize **leakage inductance** from primary to main (high-current) secondary
	- Interleave primary around secondary (or vice versa if  $N_P < N_S$ )
	- Reduces voltage spikes and power dissipation
	- Locate highest power secondary closest to primary (multi-output designs)
- Minimize transformer high-frequency **conduction loss**
	- Use bifilar or multifilar wires when necessary to reduce AC resistance
	- Interleave primary and secondary windings
	- Select core shape for minimum number of layers (wide bobbin width)
- 2. Guidelines to **optimize cross regulation**
	- Minimize **leakage inductance** *between secondary windings* as it impacts cross regulation and secondary current wave shapes
		- Wind two highest power secondaries **bifilar** for best coupling
		- Consider **DC or AC stacking** for same polarity outputs that share common GND

## **Dual-output transformer construction #1 14 : 28 : 7**



### **Primary winding 50/50 parallel split**

Parallel primary windings is a more convenient construction, but the **high dv/dt (noisy) SW node voltage** appears both on the inner and outer layers

## **Dual-output transformer construction #2 14 : 28 : 7**



### **Primary winding 50/50 series split**

Wind first **half** of primary on inside layer nearest the bobbin and the other **half** on the outside

- → Noisy node (SW) **shielded** on inside & quiet node (VIN) connects to outside layer
- $\rightarrow$  Place windings with similar dv/dt adjacent to each other to reduce interwinding capacitance
- 

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